

LAMP0504MF

Rev.F Mar.-2016

Low Capacitance TVS Array in a SOT23-6 Plastic Package.

Small package saves board space Protects up to four I/O lines & power line Low capacitance for high-speed interfaces Low leakage current and clamping voltage Low operating voltage.

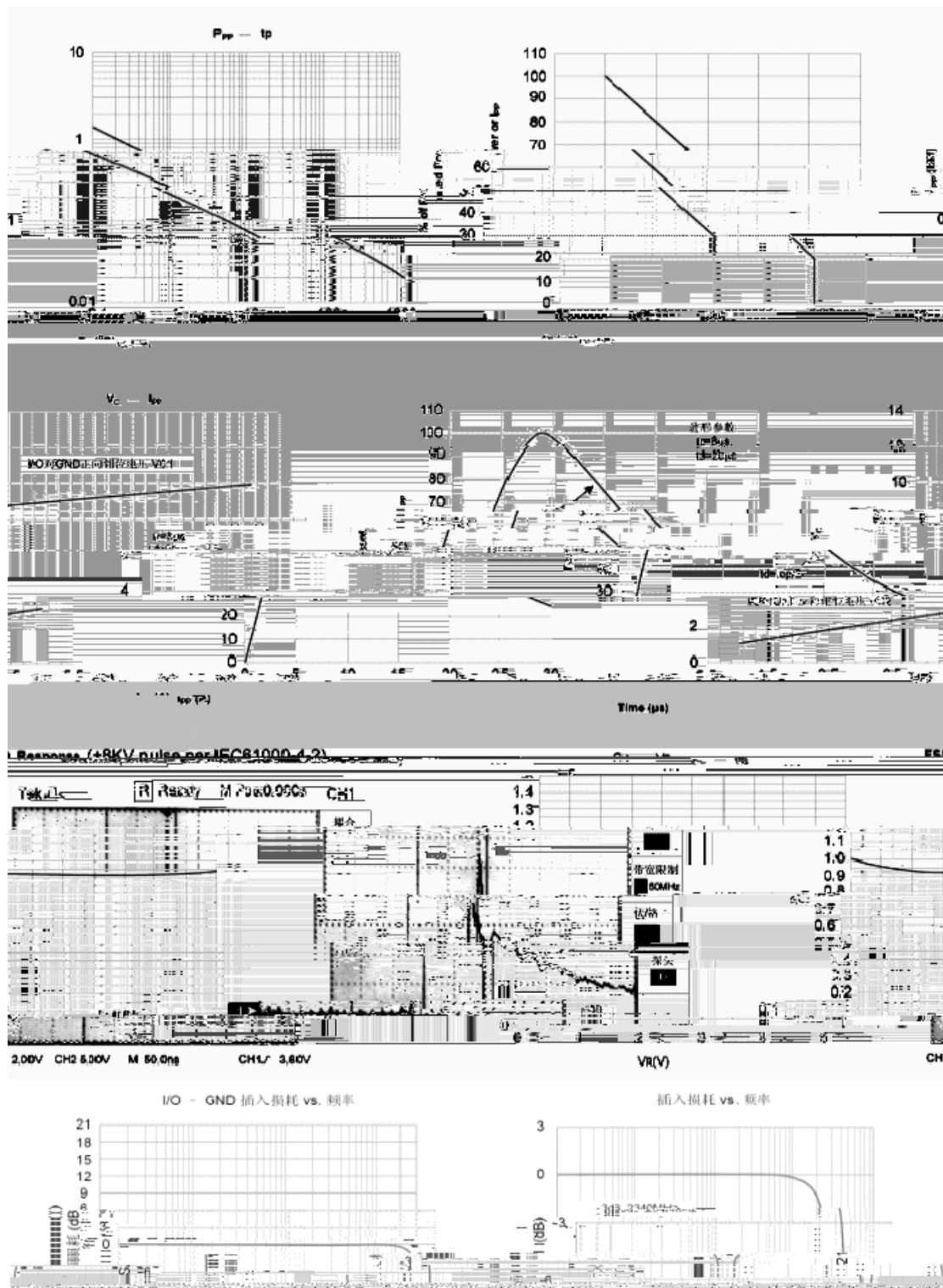
绝对最大额定值(Absolute Maximum Ratings)(Ta=25℃)

Parameter	Symbol	Rating	Unit
Peak Pulse Power (tp = 8/20μs)	PPP	150	W
Peak Pulse Current (tp = 8/20μs)	IPP	6	A
ESD per IEC 61000-4-2 (Air)	VESD 1 IEC 61000-4-2 (Air)	±15	kV
ESD per IEC 61000-4-2 (Contact)	VESD 2 IEC 61000-4-2 (Contact)	±8	kV
Operating Temperature	TOPR	-55 to 125	
Storage Temperature	TSTG	-55 to 150	

电 气 特 性 (Electrical Characteristics)(Ta=25℃)

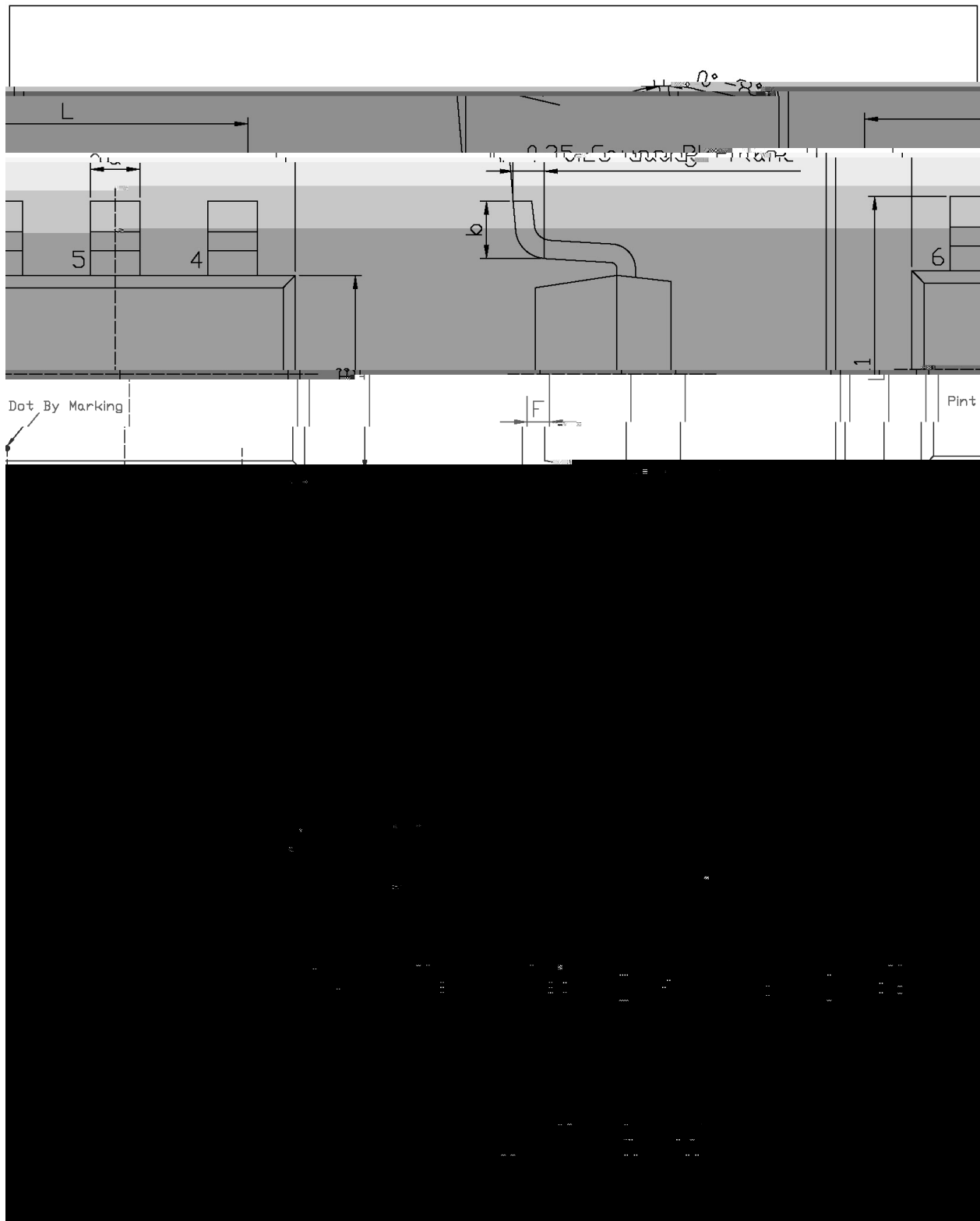
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V _{RWM}	Pin 5 to GND			5	V
Reverse Breakdown Voltage	V _{BR}	Pin 5 to GND It=1mA	6			V
Reverse Leakage Current	I _R	V _{RWM} =5V T=25℃ Pin 5 to GND			2	μA
Clamping Voltage	V _C	I _{PP} =1A tp=8/20μs Any I/O pin to GND		8.5	12	V
Junction Capacitance	C _{J1}	V _R =0V f=1MHz Any I/O pin to GND			3	pF
Junction Capacitance	C _{J2}	V _R =0V f=1MHz Between I/O pins			1.5	pF

电 压 特 性 / Electrical Characteristic Curve

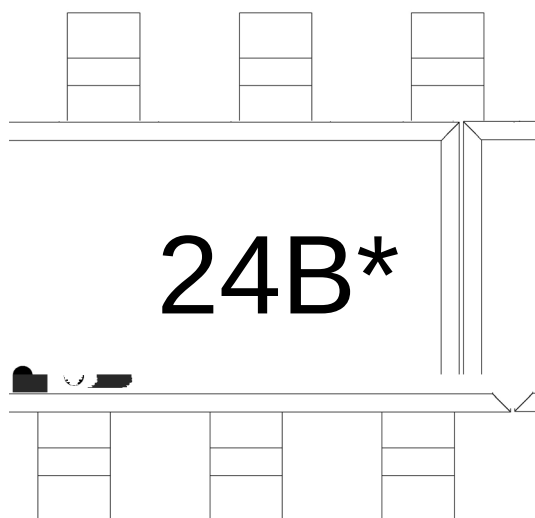




⊂ É Ò L f / Package Dimensions



1. 标记 / Marking Instructions



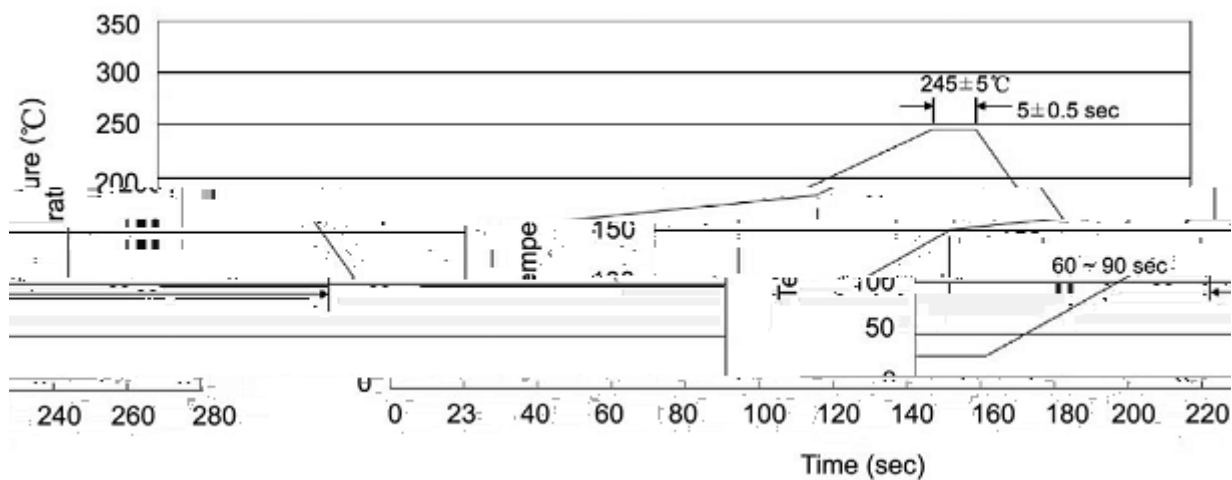
Note:

24B: Product Type Code

*: Lot No. Code, code change with Lot No.



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Note:

1. Preheating: 25~150 , Time: 60~90sec.
2. Peak Temp.: 245 ± 5 , Duration: 5 ± 0.5sec.
3. Cooling Speed: 2~10 /sec.

Resistance to Soldering Heat Test Conditions

260 ± 5 , 10 ± 1 sec. Temp.: 260 ± 5 Time: 10 ± 1 sec

Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		

Notices